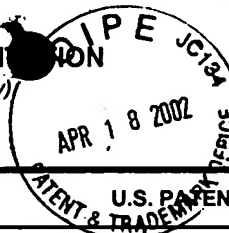


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U.S. PATENT DOCUMENTS

*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
WA	1.	6,011,304	1/2000	Mertol	257	706	
WA	2.	6,215,180	4/2001	Chen et al	257	720	
WA	3.	5,583,378	12/1996	Marrs, et al	257	710	
WA	4.	6,175,157	1/2001	Morifuji	257	777	
WA	5.	6,218,202	4/2001	Yew, et al	438	15	
WA	6.	5,907,189	5/1999	Mertol	257	787	
WA	7.	5,786,631	7/1998	Fishley, et al	257	701	
WA	8.	5,930,893	8/1999	Eaton	29	890.03	
WA	9.	5,843,810	12/1998	Sato, et al	438	123	
WA	10.	5,834,337	11/1998	Unger, et al	438	122	
WA	11.	5,475,040	12/1995	Jamison, et al	523	513	

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
WA	12.	JP362023138A	1/1987	Japan			✓ (*)	

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

(*) ABSTRACT AND CONSTITUTION

WA	13.	R. Hundadi, et al., "High Thermal Conductivity Greases,: pp. 28-32, Advanced Packaging, April 1999.						
WA	14.	Chia-Pin Chiu, et al., "Thermal Modeling of Grease-Type Interface Material in PPGA Application," pp. 57-63, Thirteenth IEEE SEMI-THERM Symposium, 1997.						

EXAMINER	DATE CONSIDERED
<i>[Signature]</i>	12/02

*EXAMINER. Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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